

# AN-2010 LM3423 Buck-Boost 2 Layer Evaluation Board

#### 1 Introduction

This wide range evaluation board showcases the LM3423 NFET controller used with a buck-boost current regulator. It is designed to drive 4 to 8 LEDs at a maximum average LED current of 700mA from a DC input voltage of 10 to 70V.

The evaluation board showcases most features of the LM3423 including PWM dimming, fault and LED status flags, output overvoltage protection and input under-voltage lockout. Note that there are two revisions of this PCB. The documentation for the latest revision (551600305-002 RevA) is shown first. The schematic, layout and bill of materials for the first revision (551600305-001 Rev1) can be found at the end of this document.

The buck-boost circuit can be easily redesigned for different specifications by changing only a few components (see the Alternate Designs section found at the end of this application note). Note that design modifications can change the system efficiency. See the *LM3421/21Q1/21Q0 LM3423/23Q1/23Q0 N-Ch Controllers for Constant Current LED Drivers* (SNVS574) data sheet for a comprehensive explanation of the device and application information.

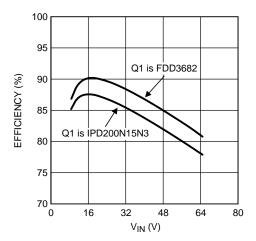


Figure 1. Efficiency with 6 Series LEDS at 700mA



# 2 Schematic for 551600305-002 REVA

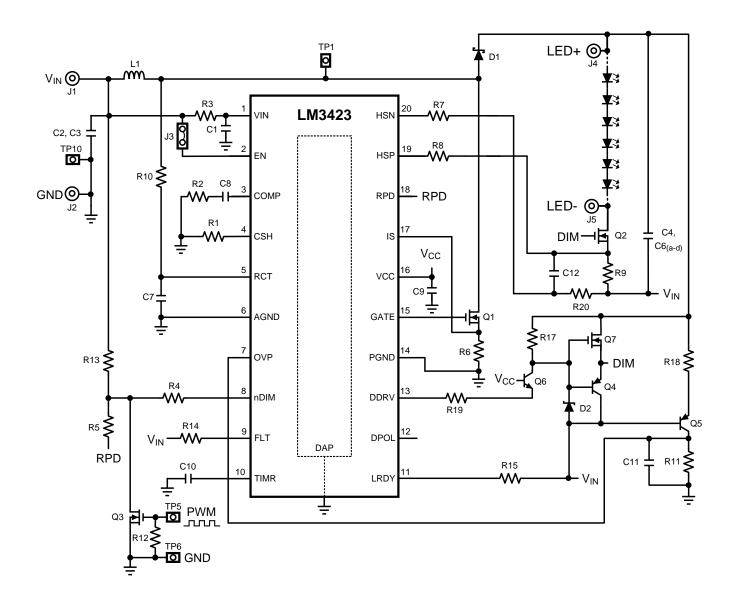


Figure 2. Board Schematic



www.ti.com Pin Descriptions

# 3 Pin Descriptions

LM3423	LM3421	Name	Description	Function	
1	1	V <sub>IN</sub>	Input Voltage	Bypass with 100 nF capacitor to AGND as close to the device as possible in the circuit board layout.	
2	2	EN	Enable	Connect to AGND for zero current shutdown or apply > 2.4V to enable device.	
3	3	COMP	Compensation	Connect a capacitor to AGND to set the compensation.	
4	4	CSH	Current Sense High	Connect a resistor to AGND to set the signal current. For analog dimming, connect a controlled current source or a potentiometer to AGND as detailed in the <i>Analog Dimming</i> section.	
5	5	RCT	Resistor Capacitor Timing	External RC network sets the predictive "off-time" and thus the switching frequency.	
6	6	AGND	Analog Ground	Connect to PGND through the DAP copper pad to provide ground return for CSH, COMP, RCT, and TIMR.	
7	7	OVP	Over-Voltage Protection	Connect to a resistor divider from V <sub>O</sub> to program output over-voltage lockout (OVLO). Turn-off threshold is 1.24V and hysteresis for turn-on is provided by 23 µA current source.	
8	8	nDIM	Dimming Input / Under-Voltage Protection	Connect a PWM signal for dimming as detailed in the <i>PWM Dimming</i> section and/or a resistor divider from V <sub>IN</sub> to program input under-voltage lockout (UVLO). Turn-on threshold is 1.24V and hysteresis for turn-off is provided by 23 µA current source.	
9	-	FLT	Fault Flag	Connect to pull-up resistor from VIN and N-channel MosFET open drain output is high when a fault condition is latched by the timer.	
10	-	TIMR	Fault Timer	Connect a capacitor to AGND to set the time delay before a sensed fault condition is latched.	
11	-	LRDY	LED Ready Flag	Connect to pull-up resistor from VIN and N-channel MosFET open drain output pulls down when the LED current is not in regulation.	
12	-	DPOL	Dim Polarity	Connect to AGND if dimming with a series P- channel MosFET or leave open when dimming with series N-channel MosFET.	
13	9	DDRV	Dim Gate Drive Output	Connect to the gate of the dimming MosFET.	
14	10	PGND	Power Ground	Connect to AGND through the DAP copper pad to provide ground return for GATE and DDRV.	
15	11	GATE	Main Gate Drive Output	Connect to the gate of the main switching MosFET.	
16	12	V <sub>cc</sub>	Internal Regulator Output	Bypass with 2.2 μF–3.3 μF ceramic capacitor to PGND.	
17	13	IS	Main Switch Current Sense	Connect to the drain of the main N-channel MosFET switch for R <sub>DS-ON</sub> sensing or to a sense resistor installed in the source of the same device.	
18	14	RPD	Resistor Pull Down	Connect the low side of all external resistor dividers (V <sub>IN</sub> UVLO, OVP) to implement "zero-current" shutdown.	
19	15	HSP	LED Current Sense Positive	Connect through a series resistor to the positive side of the LED current sense resistor.	
20	16	HSN	LED Current Sense Negative	Connect through a series resistor to the negative side of the LED current sense resistor.	
DAP (21)	DAP (17)	DAP	Thermal PAD on bottom of IC	Star ground, connecting AGND and PGND.	



# 4 Bill of Materials for 551600305-002 REVA

Qty	Part ID	Part Value	Manufacturer	Part Number	
2	C1, C12	0.1 µF X7R 10% 50V	TDK	C1608X5R1H104K	
2	C2, C8	1.0 µF X7R 10% 50V	MURATA	GRM21BR71H105KA12L KA01L	
1	C3	68 μF 20% 100V	UCC	EMVY101ARA680MKE	
1	C4	0.1 µF X7R 10% 100V	TDK	C2012X7R2A104M	
4	C6(a-d)	10 μF X7R 10% 50V (4 installed for a total of 40 μF)	TDK	C5750X7R1H106	
1	C7	1000 pF X5R 5% 100V	MURATA	C2012X5R2E102K	
1	C9	2.2 µF X7R 10% 16V	MURATA	GRM21BR71C225KA01L	
1	C10	10 nF X7R 10% 50V	PANASONIC	ECJ2VB1H103 KA12L	
1	C11	47 pF COG/NPO 5% 50V	PANASONIC	ECJ2VG1H470 KA01L	
1	D1	Schottky 100V 12A (or 6A)	VISHAY	12CWQ10FNPBF (or 6CWQ10FNPBF)	
1	D2	Zener 10V	ON-SEMI	BZX84C10-V	
4	J1, J2, J4, J5	banana jack	KEYSTONE	575-8	
1	J3	1x2 male header (with shunt tab)	SAMTEC	TSW-102-07-T-S	
1	L1	47 μH 20% 6.3A	COILCRAFT	MSS1260-473MLB	
2	Q1, Q2	NMOS 150V 50A (or 100V 32A)	INFINEON (or FAIRCHILD)	IPD200N15N3 (or FDD3682)	
2	Q3, Q7	NMOS 60V 260 mA	ON-SEMI	2N7002ET1G	
1	Q4	PNP 40V 200 mA	FAIRCHILD	MMBT3906	
1	Q5	PNP 150V 600 mA	FAIRCHILD	MMBT5401	
1	Q6	NPN 300V 500 mA	FAIRCHILD	MMBTA42	
2	R1, R11	12.4 kΩ 1%	VISHAY	CRCW080512k4FKEA	
1	R2	0Ω 1%	VISHAY	CRCW08050000Z0EA	
2	R3, R20	10Ω 1%	VISHAY	CRCW080510R0FKEA	
1	R4	16.9 kΩ 1%	VISHAY	CRCW080516k9FKEA	
3	R5, R7, R8	1.40 kΩ 1%	VISHAY	CRCW08051k40FKEA	
1	R6	0.06Ω 1% 1W	VISHAY	WSL2512R0600FEA	
1	R9	0.2Ω 1% 1W	PANASONIC	ERJ12RSFR20U	
1	R10	35.7 kΩ 1%	VISHAY	CRCW080535k7FKEA	
3	R12, R13, R19	10.0 kΩ 1%	VISHAY	CRCW080510k0FKEA	
3	R14, R15, R17	100 kΩ 1%	VISHAY	CRCW0805100kFKEA	
1	R18	432 kΩ 1%	VISHAY	CRCW0805432kFKEA	
5	TP1, TP5, TP6, TP10	turret	KEYSTONE	1502-2	
1	U1	Buck-boost controller	TI	LM3423	



# 5 PCB Layout for 551600305-002 REVA

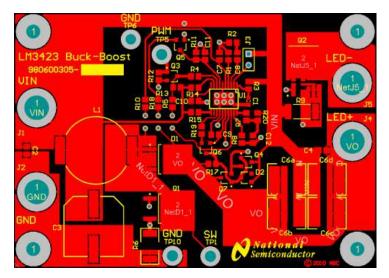


Figure 3. Top Layer

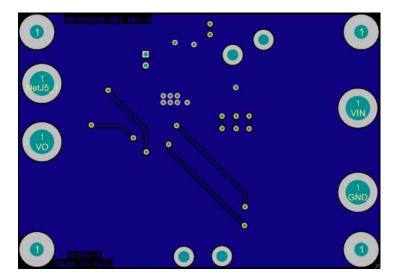


Figure 4. Bottom Layer



Design Procedure www.ti.com

### 6 Design Procedure

Refer to the *LM3421/21Q1/21Q0 LM3423/23Q1/23Q0 N-Ch Controllers for Constant Current LED Drivers* (SNVS574 data sheet for design considerations.

#### 6.1 Specifications

$$N = 6$$

$$V_{LED} = 3.5V$$

$$r_{LED} = 325 \text{ m}\Omega$$

$$V_{IN} = 24V$$

$$V_{IN-MIN} = 10V; V_{IN-MAX} = 70V$$

$$f_{SW} = 700 \text{ kHz}$$

$$V_{SNS} = 150 \text{ mV}$$

$$I_{LED} = 700 \text{ mA}$$

$$\Delta i_{L-PP} = 350 \text{ mA}$$

$$\Delta i_{LED-PP} = 50 \text{ mA}$$

$$\Delta v_{IN-PP} = 100 \text{ mV}$$

$$I_{LIM} = 4A$$

$$V_{TURN-ON} = 10V; V_{HYS} = 3.4V$$

$$V_{TURN-OFF} = 44V; V_{HYSO} = 10V$$

# 6.2 Operating Point

Solve for V<sub>O</sub> and r<sub>D</sub>:

$$V_O = N \times V_{LED} = 6 \times 3.5 V = 21 V$$
 (1)

$$r_D = N \times r_{LED} = 6 \times 325 \text{ m}\Omega = 1.95\Omega$$
 (2)

Solve for D, D',  $D_{MAX}$ , and  $D_{MIN}$ :

$$D = \frac{V_O}{V_O + V_{IN}} = \frac{21V}{21V + 24V} = 0.467$$
(3)

$$D' = 1 - D = 1 - 0.467 = 0.533$$
 (4)

$$D_{MIN} = \frac{V_O}{V_O + V_{IN-MAX}} = \frac{21V}{21V + 70V} = 0.231$$
 (5)

$$D_{MAX} = \frac{V_O}{V_O + V_{IN-MIN}} = \frac{21V}{21V + 10V} = 0.677$$
(6)

# 6.3 Switching Frequency

Assume C7 = 1 nF and solve for R10:

$$R10 = \frac{25}{f_{SW} \times C7} = \frac{25}{700 \text{ kHz} \times 1 \text{ nF}} = 35.7 \text{ k}\Omega$$
 (7)

The closest standard resistor is actually 35.7 k $\Omega$  therefore the f  $_{\text{SW}}$  is:

$$f_{SW} = \frac{25}{R10 \times C7} = \frac{25}{35.7 \text{ k}\Omega \times 1 \text{ nF}} = 700 \text{ kHz}$$
(8)



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The chosen components from Section 6.3 are:

C7 = 1 nF  
R10 = 35.7 k
$$\Omega$$
 (9)

# 6.4 Average LED Current

Solve for R9:

$$R9 = \frac{V_{SNS}}{I_{LED}} = \frac{150 \text{ mV}}{700 \text{ mA}} = 0.214\Omega$$
 (10)

Assume R1 = 12.4 k $\Omega$  and solve for R8:

$$R8 = \frac{I_{LED} \times R1 \times R9}{1.24V} = \frac{700 \text{ mA} \times 12.4 \text{ k}\Omega \times 0.2\Omega}{1.24V} = 1.4 \text{ k}\Omega$$
 (11)

The closest standard resistor for R9 is  $0.2\Omega$  and the closest for R8 (and R7) is actually 1.4 k $\Omega$  therefore  $I_{LED}$  is:

$$I_{LED} = \frac{1.24 \text{V x R8}}{\text{R9 x R1}} = \frac{1.24 \text{V x } 1.4 \text{ k}\Omega}{0.2\Omega \text{ x } 12.4 \text{ k}\Omega} = 700 \text{ mA}$$
(12)

The chosen components from Section 6.4 are:

$$R9 = 0.2\Omega$$

$$R1 = 12.4 \text{ k}\Omega$$

$$R8 = R7 = 1.4 \text{ k}\Omega$$
(13)

### 6.5 Inductor Ripple Current

Solve for L1:

$$L1 = \frac{V_{IN} \times D}{\Delta i_{L-PP} \times f_{SW}} = \frac{24V \times 0.467}{350 \text{ mA} \times 700 \text{ kHz}} = 46 \text{ }\mu\text{H}$$
(14)

The closest standard inductor is 47  $\mu$ H therefore the actual  $\Delta i_{L-PP}$  is:

$$\Delta i_{L-PP} = \frac{V_{IN} \times D}{L1 \times f_{SW}} = \frac{24V \times 0.467}{47 \ \mu H \times 700 \ kHz} = 340 \ mA \tag{15}$$

Determine minimum allowable RMS current rating:

$$I_{L\text{-RMS}} = \frac{I_{LED}}{D'} \times \sqrt{1 + \frac{1}{12} \times \left( \frac{\Delta I_{L\text{-PP}} \times D'}{I_{LED}} \right)^2}$$

$$I_{L-RMS} = \frac{700 \text{ mA}}{0.533} \text{ x} \sqrt{1 + \frac{1}{12} \text{ x} \left( \frac{340 \text{ mA x } 0.533}{700 \text{ mA}} \right)^2}$$

$$I_{L-RMS} = 1.32A \tag{16}$$

The chosen component from Section 6.5 is:

$$\boxed{\mathsf{L}1 = 47 \; \mu\mathsf{H}} \tag{17}$$

#### 6.6 Output Capacitance

Solve for Co:

$$C_{O} = \frac{I_{LED} x D}{r_{D} x \Delta i_{LED-PP} x f_{SW}}$$

$$C_{O} = \frac{700 \text{ mA} \times 0.467}{1.95\Omega \times 50 \text{ mA} \times 700 \text{ kHz}} = 4.79 \text{ }\mu\text{F}$$
(18)



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A total value of 40  $\mu$ F (using 4 10  $\mu$ F X7R ceramic capacitors) is chosen therefore the actual  $\Delta i_{\text{LED-PP}}$  is:

$$\Delta i_{LED-PP} = \frac{I_{LED} \times D}{r_D \times C_O \times f_{SW}}$$

$$\Delta i_{LED-PP} = \frac{700 \text{ mA} \times 0.467}{1.95\Omega \times 40 \text{ µF} \times 700 \text{ kHz}} = 6 \text{ mA}$$
(19)

Determine minimum allowable RMS current rating:

$$I_{\text{CO-RMS}} = I_{\text{LED}} \times \sqrt{\frac{D_{\text{MAX}}}{1 - D_{\text{MAX}}}} = 700 \text{ mA} \times \sqrt{\frac{0.677}{1 - 0.677}} = 1.01 \text{A}$$
(20)

The chosen components from Section 6.6 are:

$$C6 = 4 \times 10 \ \mu\text{F}$$
 (21)

#### 6.7 Peak Current Imit

Solve for R6:

$$R6 = \frac{245 \text{ mV}}{I_{\text{LIM}}} = \frac{245 \text{ mV}}{4A} = 0.061\Omega$$
 (22)

The closest standard resistor is 0.06  $\Omega$  therefore I<sub>LIM</sub> is:

$$I_{\text{LIM}} = \frac{245 \text{ mV}}{R6} = \frac{245 \text{ mV}}{0.06\Omega} = 4.1 \text{A}$$
 (23)

The chosen component from Section 6.7 is:

$$R6 = 0.06\Omega$$

#### 6.8 Loop Compensation

 $\omega_{P1}$  is approximated:

$$\omega_{P1} = \frac{1 + D}{r_D \times C_O} = \frac{1.467}{1.95\Omega \times 40 \ \mu F} = 19k \frac{rad}{sec}$$
 (25)

 $\omega_{Z1}$  is approximated:

$$\omega_{Z1} = \frac{r_D \times D'^2}{D \times L1} = \frac{1.95\Omega \times 0.533^2}{0.467 \times 47 \ \mu H} = 25k \ \frac{rad}{sec}$$
 (26)

 $T_{U0}$  is approximated:

$$T_{U0} = \frac{D' \times 620V}{(1 + D) \times I_{LED} \times R6} = \frac{0.533 \times 620V}{1.467 \times 700 \text{ mA} \times 0.06\Omega} = 5360$$
 (27)

To ensure stability, calculate  $\omega_{P2}$ :

$$\omega_{P2} = \frac{\min(\omega_{P1}, \, \omega_{Z1})}{5 \times T_{U0}} = \frac{\omega_{P1}}{5 \times 5360} = \frac{19k \frac{\text{rad}}{\text{sec}}}{5 \times 5360} = 0.709 \frac{\text{rad}}{\text{sec}}$$
(28)

Solve for C8:

$$C8 = \frac{1}{\omega_{P2} \times 5e^{6}\Omega} = \frac{1}{0.709 \frac{\text{rad}}{\text{sec}} \times 5e^{6}\Omega} = 0.28 \,\mu\text{F}$$
(29)

To attenuate switching noise, calculate  $\omega_{P3}$ :

$$\omega_{P3} = \max (\omega_{P1}, \omega_{Z1}) \times 10 = \omega_{Z1} \times 10$$

$$\omega_{P3} = 25k \frac{\text{rad}}{\text{sec}} \times 10 = 250k \frac{\text{rad}}{\text{sec}}$$
(30)

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Assume R20 =  $10\Omega$  and solve for C12:

$$C12 = \frac{1}{10\Omega \times \omega_{P3}} = \frac{1}{10\Omega \times 250k \frac{\text{rad}}{\text{sec}}} = 0.4 \,\mu\text{F}$$
(31)

Since PWM dimming can be evaluated with this board, a much larger compensation capacitor C8 = 1.0  $\mu$ F is chosen and a smaller high frequency capacitor C12 = 0.1  $\mu$ F is chosen.

The chosen components from Section 6.8 are:

C8 = 1.0 
$$\mu$$
F  
R20 = 10 $\Omega$   
C12 = 0.1  $\mu$ F

#### 6.9 Input Capacitance

Solve for the minimum C<sub>IN</sub>:

$$C_{IN} = \frac{I_{LED} \times D}{\Delta V_{IN-PP} \times f_{SW}} = \frac{700 \text{ mA} \times 0.467}{100 \text{ mV} \times 700 \text{ kHz}} = 4.67 \text{ }\mu\text{F}$$
(33)

To minimize power supply interaction a much larger capacitance of 68  $\mu F$  is used, therefore the actual  $\Delta v_{\text{IN-PP}}$  is much lower.

Determine minimum allowable RMS current rating:

$$I_{\text{CO-RMS}} = I_{\text{LED}} \times \sqrt{\frac{D_{\text{MAX}}}{1 - D_{\text{MAX}}}} = 700 \text{ mA} \times \sqrt{\frac{0.677}{1 - 0.677}} = 1.01 \text{A}$$
(34)

The chosen components from Section 6.9 are:

$$C3 = 68 \,\mu\text{F}$$
 (35)

#### 6.10 NFET

Determine minimum Q1 voltage rating and current rating:

$$V_{T-MAX} = V_{IN-MAX} + V_O = 70V + 21V = 91V$$
(36)

$$I_{T-MAX} = \frac{0.677}{1 - 0.677} \times 700 \text{ mA} = 1.46A \tag{37}$$

A 100V NFET is chosen with a current rating of 40A due to the low  $R_{DS-ON} = 50 \text{ m}\Omega$ . Determine  $I_{T-RMS}$  and  $P_{T}$ :

$$I_{T-RMS} = \frac{I_{LED}}{D'} \times \sqrt{D} = \frac{700 \text{ mA}}{0.533} \times \sqrt{0.467} = 897 \text{ mA}$$
(38)

$$P_{T} = I_{T-RMS}^{2} \times R_{DSON} = 897 \text{ mA}^{2} \times 50 \text{ m}\Omega = 40 \text{ mW}$$
(39)

The chosen component from Section 6.10 is:

$$Q1 \rightarrow 40A, 100V, DPAK$$
 (40)

#### **6.11 DIODE**

Determine minimum D1 voltage rating and current rating:

$$V_{RD-MAX} = V_{IN-MAX} + V_{O} = 70V + 21V = 91V$$
(41)

$$I_{D-MAX} = I_{LED} = 700 \text{ mA} \tag{42}$$

A 100V diode is chosen with a current rating of 12A and  $V_D = 600$  mV. Determine  $P_D$ :

$$P_D = I_D \times V_{FD} = 700 \text{ mA} \times 600 \text{ mV} = 420 \text{ mW}$$
 (43)



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The chosen component from Section 6.11 is:

$$D1 \rightarrow 12A, 100V, DPAK$$
(44)

#### 6.12 Input UVLO

Since PWM dimming will be evaluated, a three resistor network will be used. Assume R13 = 10 k $\Omega$  and solve for R5:

$$R5 = \frac{1.24 \text{V} \times R13}{\text{V}_{\text{TURN-ON}} - 1.24 \text{V}} = \frac{1.24 \text{V} \times 10 \text{ k}\Omega}{10 \text{V} - 1.24 \text{V}} = 1.42 \text{ k}\Omega$$
(45)

The closest standard resistor is 1.4 k $\Omega$  therefore  $V_{TURN-ON}$  is:

$$V_{\text{TURN-ON}} = \frac{1.24 \text{V x } (\text{R5} + \text{R13})}{\text{R5}}$$

$$V_{\text{TURN-ON}} = \frac{1.24 \text{V x } (1.4 \text{ k}\Omega + 10 \text{ k}\Omega)}{1.4 \text{ k}\Omega} = 10.1 \text{V}$$
(46)

Solve for R4:

$$R4 = \frac{R5 \times (V_{HYS} - 23 \,\mu\text{A} \times R13)}{23 \,\mu\text{A} \times (R5 + R13)}$$

$$R4 = \frac{1.4 \,k\Omega \times (3.4 \text{V} - 23 \,\mu\text{A} \times 10 \,k\Omega)}{23 \,\mu\text{A} \times (1.4 \,k\Omega + 10 \,k\Omega)} = 16.9 \,k\Omega$$
(47)

The closest standard resistor is 16.9 k $\Omega$  making  $V_{\text{HYS}}$ :

$$V_{HYS} = \frac{23 \,\mu\text{A} \times \text{R4} \times (\text{R5} + \text{R13})}{\text{R5}} + 23 \,\mu\text{A} \times \text{R13}$$

$$V_{HYS} = \frac{23 \,\mu\text{A} \times 16.9 \,k\Omega \times (1.4 \,k\Omega + 10 \,k\Omega)}{1.4 \,k\Omega} + 23 \,\mu\text{A} \times 10 \,k\Omega = 3.4 \text{V}$$
(48)

The chosen components from Section 6.12 are:

$$R5 = 1.4 \text{ k}\Omega$$

$$R13 = 10 \text{ k}\Omega$$

$$R4 = 16.9 \text{ k}\Omega$$
(49)

# 6.13 Output OVLO

Solve for R18:

$$R18 = \frac{V_{HYSO}}{23 \,\mu\text{A}} = \frac{10V}{23 \,\mu\text{A}} = 435 \,\text{k}\Omega \tag{50}$$

The closest standard resistor is 432 k $\Omega$  therefore  $V_{HYSO}$  is:

$$V_{HYSO} = R18 \times 23 \ \mu A = 432 \ k\Omega \times 23 \ \mu A = 9.9V$$
 (51)

Solve for R11:

$$R11 = \frac{1.24 \text{V} \times R18}{\text{V}_{\text{TURN-OFF}} - 620 \text{ mV}} = \frac{1.24 \text{V} \times 432 \text{ k}\Omega}{44 \text{V} - 620 \text{ mV}} = 12.3 \text{ k}\Omega$$
(52)

The closest standard resistor is 12.4 k $\Omega$  making  $V_{TURN-OFF}$ :

$$V_{\text{TURN-OFF}} = \frac{1.24 \text{V} \times (\text{R}11 + \text{R}18)}{\text{R}11}$$

$$V_{\text{TURN-OFF}} = \frac{1.24 \text{V} \times (0.5 \times 12.4 \text{ k}\Omega + 432 \text{ k}\Omega)}{12.4 \text{ k}\Omega} = 44 \text{V}$$
(53)



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The chosen components from Section 6.13 are:

R11 =  $12.4 \text{ k}\Omega$ R18 =  $432 \text{ k}\Omega$  (54)

#### 6.14 PWM Dimming

The LM3423 Buck-boost Evaluation board is configured to demonstrate PWM dimming of the LEDs. For best operation, use a PWM signal that has greater than 3V amplitude at a frequency between 120Hz and 5kHz. Apply the PWM signal to the BNC connector (J6) and the inverted signal (seen by the nDIM pin) can be monitored at TP5.

The output PWM drive signal (DDRV) is level shifted to the floating LED stack using several components (R19, R17, Q4, Q6, Q7, and D2) and ultimately controls the series dimming FET (Q2). This level shift adds a several microsecond delay from input to output as seen in the *Typical Waveforms* section. This delay, along with the time it takes to slew the LED current from zero to its nominal value, limits the contrast ratio for a given dimming frequency.

Using the evaluation board (24V input, 21V output), at 5kHz dimming frequency the best case contrast ratio is approximately 40:1, but at 200Hz the same system is more like 1000:1 ratio. In general, contrast ratios much above 2000:1 are not possible for any operating point using the LM3423 buck-boost evaluation board.

### 6.15 Fault and LED Current Monitoring

The LM3423 has a fault detection flag in the form of an open-drain NFET at the FLT pin. Using the external pull-up resistor (R14) to VIN, the fault status can be monitored at the FLT pin (high = fault). The fault timer interval is set with the capacitor (C10) from TIMR to GND (10nF yields roughly 1ms). If a fault is detected that exceeds the programmed timer interval, such as an output over-voltage condition, the FLT pin transitions from high to low and internally GATE and DDRV are latched off. To reset the device once the fault is removed, either the input power must be cycled or the EN pin must be toggled.

This can be tested directly with the evaluation board by opening the LED load. An OVP fault will occur which disables GATE and DDRV. Then if the LEDs are reconnected, the EN pin jumper (J3) can be removed and reinserted to restart normal operation of the LM3423.

The LED status flag (LRDY) can be seen by monitoring TP4. LRDY is also an open-drain NFET connection which has an external pull-up resistor (R15) to  $V_{IN}$ . If the LED current is in regulation the voltage at TP4 will be high, but when it falls out of regulation the NFET turns on and pulls TP4 low. The LM3423 datasheet lists all of the conditions that affect LRDY. FLT. and TIMR.



Typical Waveforms www.ti.com

# 7 Typical Waveforms

 $T_A = +25$ °C,  $V_{IN} = 24$ V and  $V_O = 21$ V.

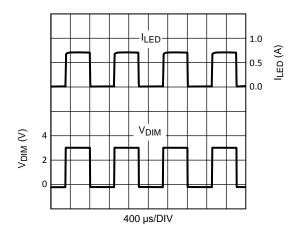


Figure 5. 1kHz 50% PWM DIMMING TP5 dim voltage (V<sub>DIM</sub>) LED current (I<sub>LED</sub>)

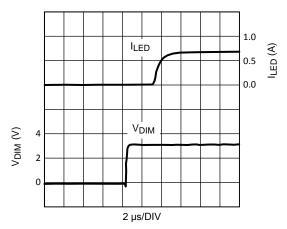
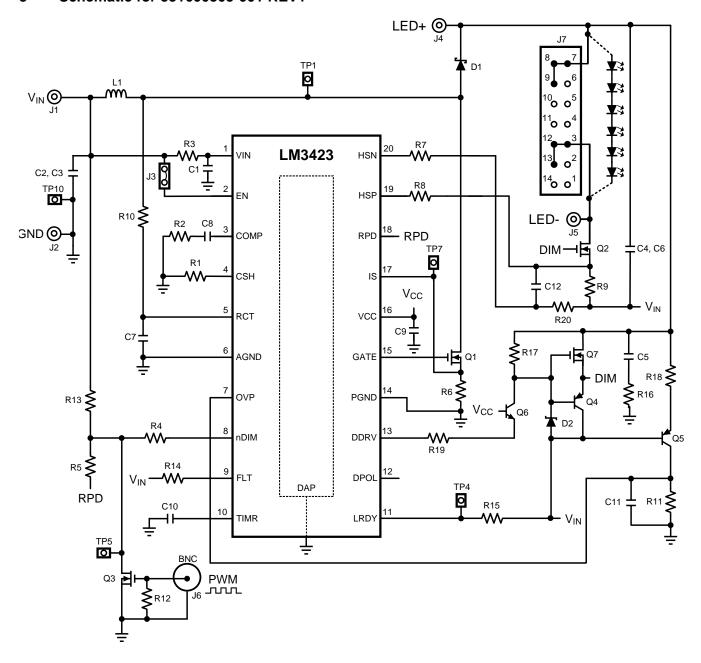


Figure 6. 1kHz 50% PWM DIMMING (Rising Edge) TP5 dim voltage ( $V_{\text{DIM}}$ ) LED current ( $I_{\text{LED}}$ )



# 8 Schematic for 551600305-001 REV1





# 9 PCB Layout for 551600305-001 REV1

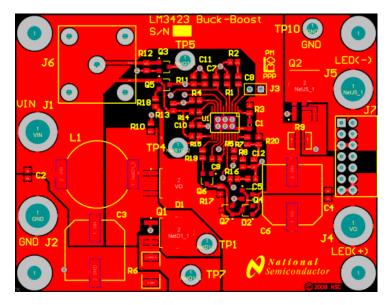


Figure 7. Top Layer

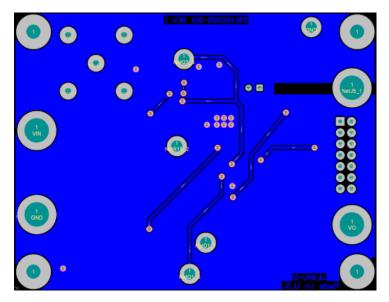


Figure 8. Bottom Layer



# 10 Bill of Materials for 551600305-001 REV1

Qty	Part ID	Part Value	Manufacturer	Part Number	
2	C1, C12	0.1 μF X7R 10% 50V	TDK	C1608X5R1H104K	
2	C2, C8	1.0 μF X7R 10% 50V	MURATA	GRM21BR71H105KA12L KA01L	
1	C3	68 μF 20% 100V	UCC	EMVY101ARA680MKE	
1	C4	0.1 μF X7R 10% 100V	TDK	C2012X7R2A104M	
1	C5	DNP			
4	C6	10 μF X7R 10% 50V (4 installed for a total of 40 μF)	TDK	C5750X7R1H106	
1	C7	1000 pF X5R 5% 100V	MURATA	C2012X5R2E102K	
1	C9	2.2 μF X7R 10% 16V	MURATA	GRM21BR71C225KA01L	
1	C10	10 nF X7R 10% 50V	PANASONIC	ECJ2VB1H103 KA12L	
1	C11	47 pF COG/NPO 5% 50V	PANASONIC	ECJ2VG1H470 KA01L	
1	D1	Schottky 100V 7A	VISHAY	6CWQ10FNPBF	
1	D2	Zener 10V	ON-SEMI	BZX84C10-V	
4	J1, J2, J4, J5	banana jack	KEYSTONE	575-8	
1	J3	1x2 male header (with shunt tab)	SAMTEC	TSW-102-07-T-S	
1	J6	BNC connector	AMPHENOL	112536	
1	J7	DNP			
1	L1	47 μH 20% 6.3A	COILCRAFT	MSS1260-473MLB	
2	Q1, Q2	NMOS 100V 40A	VISHAY	SUD40N10-25	
2	Q3, Q7	NMOS 60V 260 mA	ON-SEMI	2N7002ET1G	
1	Q4	PNP 40V 200 mA	FAIRCHILD	MMBT3906	
1	Q5	PNP 150V 600 mA	FAIRCHILD	MMBT5401	
1	Q6	NPN 300V 500 mA	FAIRCHILD	MMBTA42	
2	R1, R11	12.4 kΩ 1%	VISHAY	CRCW080512k4FKEA	
1	R2	0Ω 1%	VISHAY	CRCW08050000Z0EA	
2	R3, R20	10Ω 1%	VISHAY	CRCW080510R0FKEA	
1	R4	16.9 kΩ 1%	VISHAY	CRCW080516k9FKEA	
3	R5, R7, R8	1.40 kΩ 1%	VISHAY	CRCW08051k40FKEA	
1	R6	0.06Ω 1% 1W	VISHAY	WSL2512R0600FEA	
1	R9	0.2Ω 1% 1W	PANASONIC	ERJ12RSFR20U	
1	R10	35.7 kΩ 1%	VISHAY	CRCW080535k7FKEA	
3	R12, R13, R19	10.0 kΩ 1%	VISHAY	CRCW080510k0FKEA	
3	R14, R15, R17	100 kΩ 1%	VISHAY	CRCW0805100kFKEA	
1	R16	DNP			
1	R18	432 kΩ 1%	VISHAY	CRCW0805432kFKEA	
5	TP1, TP4, TP5, TP7, TP10	turret	KEYSTONE	1502-2	
1	U1	Buck-boost controller	TI	LM3423	



Alternate Designs www.ti.com

# 11 Alternate Designs

Alternate designs with the LM3423 evaluation board are possible with very few changes to the existing hardware. The evaluation board FETs and diodes are already rated higher than necessary for design flexibility. The input UVLO, output OVP, input and output capacitance can remain the same for the designs shown below. These alternate designs can be evaluated by changing only R9, R10, and L1.

Table 1 gives the main specifications for four different designs and the corresponding values for R9, R10, and L1. PWM dimming can be evaluated with any of these designs.

**Table 1. Alternate Designs Specifications** 

Specification / Component	Design 1	Design 2	Design 3	Design 4
V <sub>IN</sub>	10V - 45V	15V - 50V	20V - 55V	25V - 60V
Vo	14V	21V	28V	35V
$f_{SW}$	600kHz	700kHz	500kHz	700kHz
I <sub>LED</sub>	2A	500mA	2.5A	1.25A
R9	0.05Ω	0.2Ω	0.04Ω	0.80.0
R10	41.2 kΩ	35.7 kΩ	49.9 kΩ	35.7 kΩ
L1	22µH	68µH	15µH	33µH

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